

WHAT IS CLAIMED IS:

1. A printed wiring board comprising:  
a portion containing a signal line and a signal line gap;  
and

5 at least one of a ground and a power supply plane formed  
with at least one slit,

wherein a shape and a position of the slit formed in the  
ground or power supply plane are determined so that the slit  
does not exist in a section opposed to the portion containing  
10 the signal line and the signal line gap.

2. A printed wiring board according to claim 1,  
wherein the portion containing the signal line and the signal  
line gap is a plane having one or more ground guards, and the  
15 shape and the position of at least one of the slits formed in  
the ground or power supply plane are determined so that the  
slit exists in the section opposed to the ground guard.

3. A printed wiring board according to claim, wherein  
20 the slit is a slit formed to satisfy a condition concerning  
a maximum conductor area in UL796 standard.

4. A method for manufacturing a printed wiring board  
comprising a portion containing a signal line and a signal line  
25 gap, and at least one of a ground and a power supply plane,

said method comprising:

a shape and position determination step of determining the number of slits to be formed in the ground or power supply plane and the shape and the position of each slit so that the portion containing the signal line and the signal line gap does not exist in a section opposed to each slit and a predetermined condition is satisfied; and

a printed wiring board manufacturing step of manufacturing a printed wiring board with the number of slits formed in the ground or power supply plane and the shape and the position of each slit matching a processing result in said shape and position determination step.

5. A printed wiring board manufacturing method according to claim 4, wherein in said shape and position determination step, the shape and the position of each slit are determined so that the slit is opposed to either a section wherein a portion containing the signal line and the signal line gap exists or a section wherein a ground guard exists.

6. A printed wiring board manufacturing method according to claim 4, wherein in said shape and position determination step, the shape and the position of each slit are determined so that the slit is opposed to any of a section wherein a wiring element does not exist, a section wherein a

ground guard exists, or a section wherein a power supply line or a signal line for transmitting a signal of a predetermined frequency or less exists.

- 5           7.    A printed wiring board manufacturing method according to claim 4, wherein the predetermined condition is a condition concerning a maximum conductor area in UL796 standard.